

# In-situ fabrication of 3D printed carbon fiber reinforced polymer composites



Ke Chen<sup>a</sup>, Wuxun Chen<sup>a</sup>, Lili Chen<sup>a,\*</sup>, Liuhua Chen<sup>a</sup>, Changbin Chen<sup>a</sup>, Jialin Chen<sup>a</sup>, Liang Chen<sup>a</sup>, Xiaowen Chen<sup>a</sup>, Kuanjun Chen<sup>a</sup>, Lili Chen<sup>a</sup>, Xugang Chen<sup>a</sup>, Tianping Chen<sup>a</sup>

<sup>a</sup> Gemmological Institute, China University of Geosciences, Wuhan 430074, PR China  
<sup>b</sup> Hubei Gem and Jewelry Engineering Technology Research Center, Wuhan 430074, PR China  
<sup>c</sup> School of Materials Science and Engineering, Huazhong University of Science and Technology, Wuhan 430074, PR China  
<sup>d</sup> Mechanical Engineering, University of Birmingham, Birmingham B15 2TT, UK  
<sup>e</sup> School of Electrical and Electronic Engineering, Huazhong University of Science and Technology, Wuhan 430074, PR China  
<sup>f</sup> WMG, Materials Engineering Centre, University of Warwick, CV4 7AL Coventry, UK

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## ABSTRACT

Carbon fiber reinforced polymer (CFRP) composites (3DG) fabricated via... (SLM) (3D) (CVD) (EMMI) (SE) 47.8 B. 2.7 GH (SE) 32.3 B. 1.2-18 GH. SLM

## 1. Introduction

Graphene is a 2D material with a thickness of one carbon atom... (2630 nm<sup>-2</sup>)... (5000 W m<sup>-1</sup> K<sup>-1</sup>)... (3DG) (99.7%)... (0.6 nm<sup>-2</sup>)

(2DG), (EMMI) (3DG) (9) (10) (11) (12) (13) (14) (15) (16) B

\*Corresponding author. E-mail address: [llchen@cgic.cug.edu.cn](mailto:llchen@cgic.cug.edu.cn) (L. Chen).

... T x ... (u, ...  
... 3DG W ... 3DG. B ...  
... H W ...  
... 17,18.  
... 3DG W ...  
... 19.  
... (SLM), ...  
... (AM) ...  
... (3D) ...  
... in-situ ...  
... SLM ...  
... 20,  
... 21, ... 22. C ...  
... C ...  
... CVD ...  
... (< 0.001 ...%) ...  
... 23. W ...  
... (> 0.1 ...%) 17, ...  
... 24. H ...  
... SLM ...  
... (1000-1100 ...). F ...  
... SLM ... 25.  
... T ...  
... 3DG/ ... (3DG/C) ...  
... SLM ... CVD ...  
... A ...  
... SLM ...



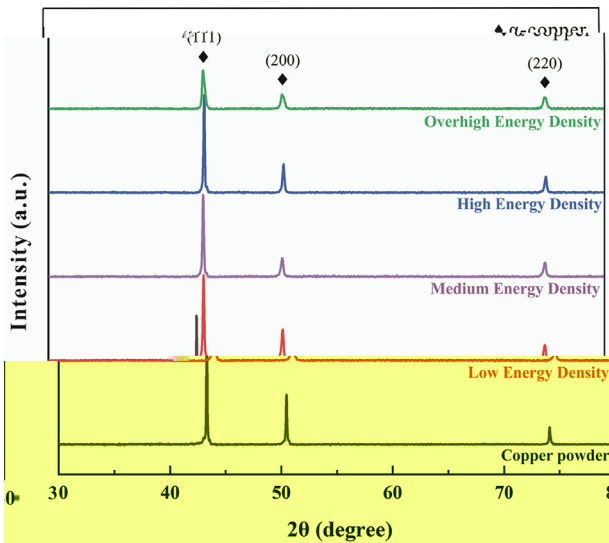


Fig. 3. XRD patterns of copper powder at different energy densities. (a) 3000 J/mm<sup>3</sup>, (b) 857 J/mm<sup>3</sup>, (c) 285 J/mm<sup>3</sup>, (d) 128 J/mm<sup>3</sup>.

3.1.2. Formation of anisotropic microstructure under different volumetric energy density

The XRD patterns of copper powder at different energy densities are shown in Fig. 3. The main peaks are indexed to the (111), (200), and (220) planes of copper powder. The peak intensity of the (111) plane is significantly higher than that of the (200) and (220) planes, indicating a strong preferential orientation of the copper powder particles along the (111) plane. This preferential orientation is more pronounced at higher energy densities, as evidenced by the increasing intensity of the (111) peak relative to the other peaks.

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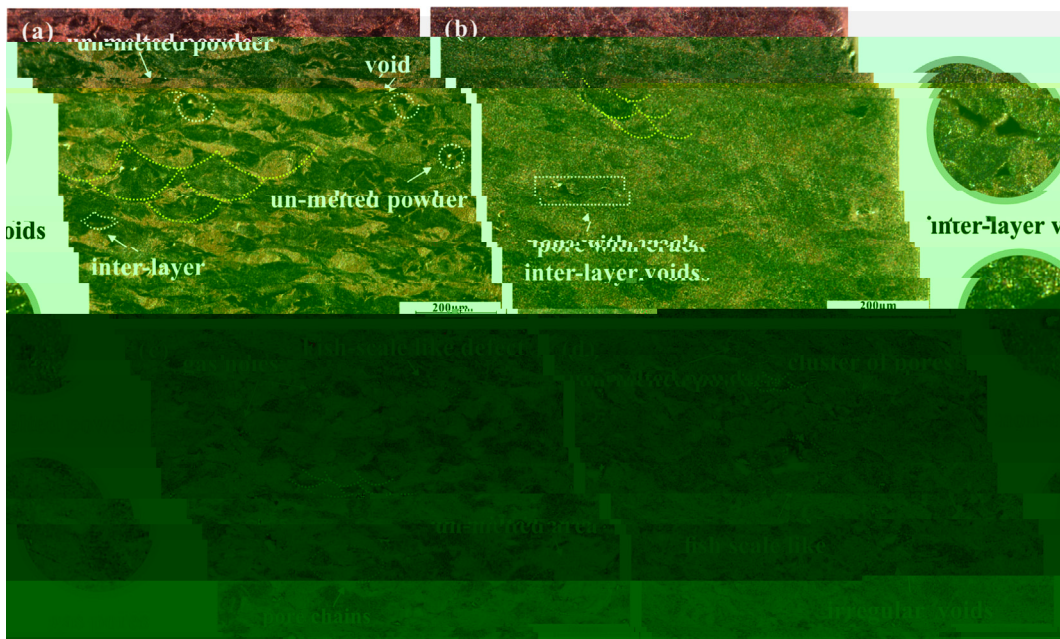


Fig. 4. SEM micrographs of SLM-processed copper powder at different energy densities: (a) 3000 J/mm<sup>3</sup>, (b) 857 J/mm<sup>3</sup>, (c) 285 J/mm<sup>3</sup>, (d) 128 J/mm<sup>3</sup>.



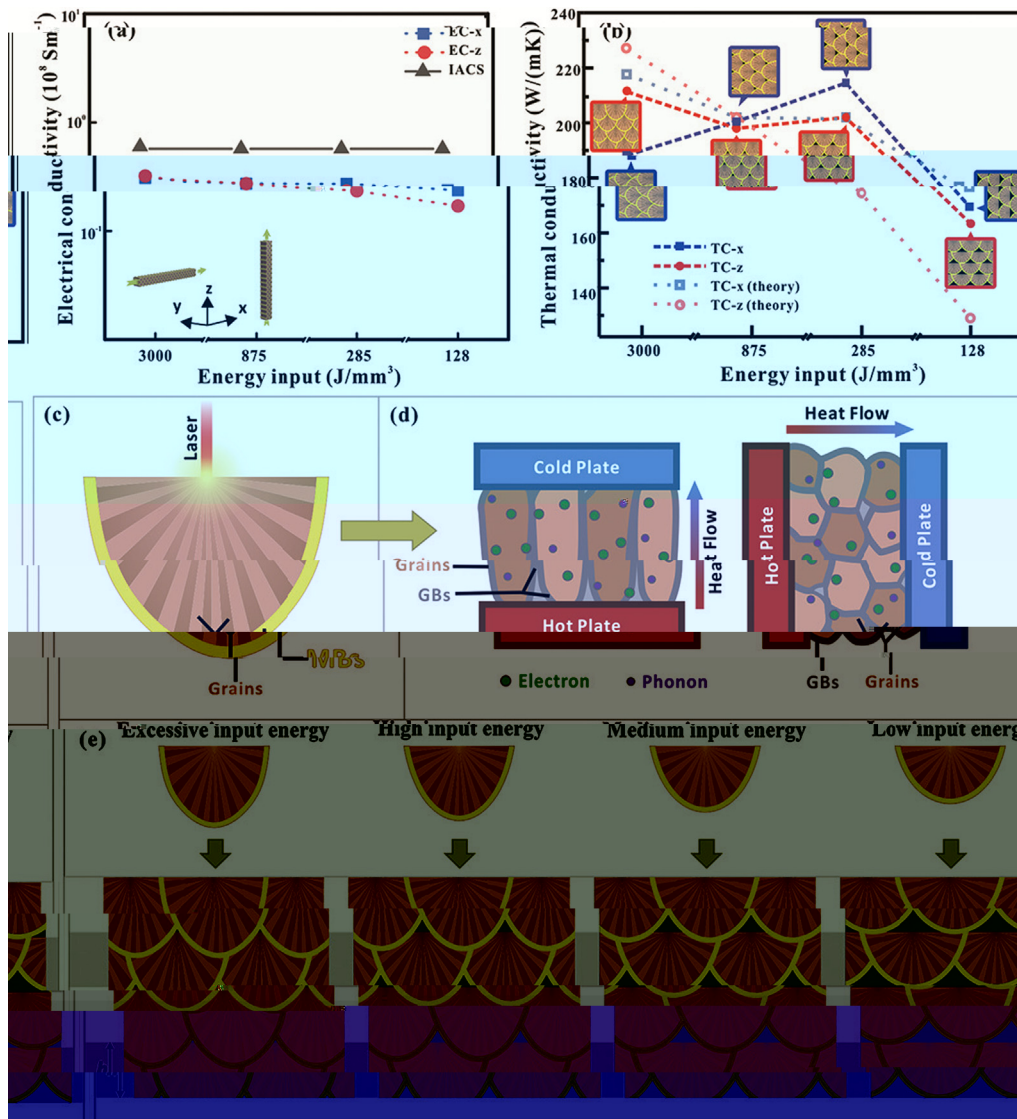


Fig. 7. (a) Electrical conductivity of the porous scaffold as a function of energy input; (b) thermal conductivity of the porous scaffold as a function of energy input; (c) schematic of the laser irradiation on the porous scaffold; (d) schematic of the heat flow through the porous scaffold; (e) schematic of the porous scaffold morphology at different energy input levels.

3.3. Morphology and structure of CVD 3DG/Cu porous scaffolds

### 3.3. Morphology and structure of CVD 3DG/Cu porous scaffolds

Figure 8 shows the morphology and structure of the CVD 3DG/Cu porous scaffolds. The scaffolds were prepared by laser-assisted CVD. The porous structure was characterized by SEM and EDS. The scaffolds exhibited a porous structure with interconnected pores. The pore size was approximately 450 μm. The scaffolds were composed of Cu and Cu<sub>2</sub>O. The scaffolds were prepared by laser-assisted CVD. The porous structure was characterized by SEM and EDS. The scaffolds exhibited a porous structure with interconnected pores. The pore size was approximately 450 μm. The scaffolds were composed of Cu and Cu<sub>2</sub>O. The scaffolds were prepared by laser-assisted CVD. The porous structure was characterized by SEM and EDS. The scaffolds exhibited a porous structure with interconnected pores. The pore size was approximately 450 μm. The scaffolds were composed of Cu and Cu<sub>2</sub>O.

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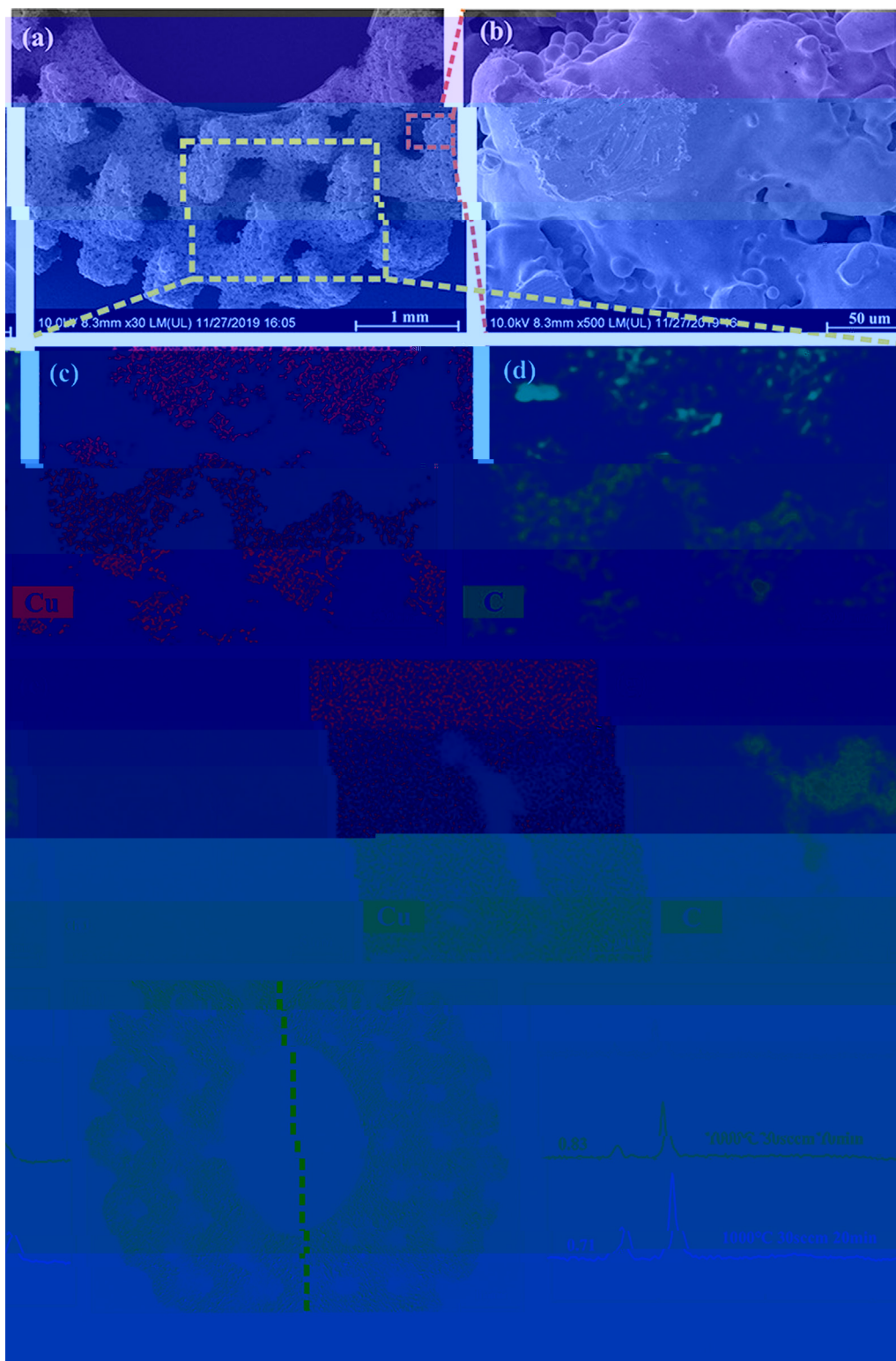


Fig. 8. (a) SEM image of 3DG/C porous scaffold; (b) SEM image of 3DG/C porous scaffold; (c) EDS map of 3DG/C porous scaffold; (d) EDS map of 3DG/C porous scaffold with overlaid XRD patterns. The XRD patterns show peaks at 0.71 and 0.83, corresponding to 1000°C 30min and 1000°C 30min+30min treatments, respectively.

SEM image of 3DG/C porous scaffold. The image shows a porous structure with interconnected struts. The scale bar indicates 1 mm. The SEM image of 3DG/C porous scaffold at 50 μm scale shows a more detailed view of the porous structure. The EDS map of 3DG/C porous scaffold shows the distribution of Cu (red) and C (green). The EDS map of 3DG/C porous scaffold with overlaid XRD patterns shows the distribution of Cu (red) and C (green) and the XRD patterns. The XRD patterns show peaks at 0.71 and 0.83, corresponding to 1000°C 30min and 1000°C 30min+30min treatments, respectively.

### 3.4. Thermal property and EMI shielding effectiveness of 3DG/Cu porous scaffolds

The thermal property and EMI shielding effectiveness of 3DG/Cu porous scaffolds were investigated. The TGA curves of 3DG/C porous scaffolds are shown in Fig. 9. The TGA curves show that the 3DG/C porous scaffolds have a high thermal stability. The weight loss of 3DG/C porous scaffolds is 26.8% at 1000°C and 14.8% at 1200°C.

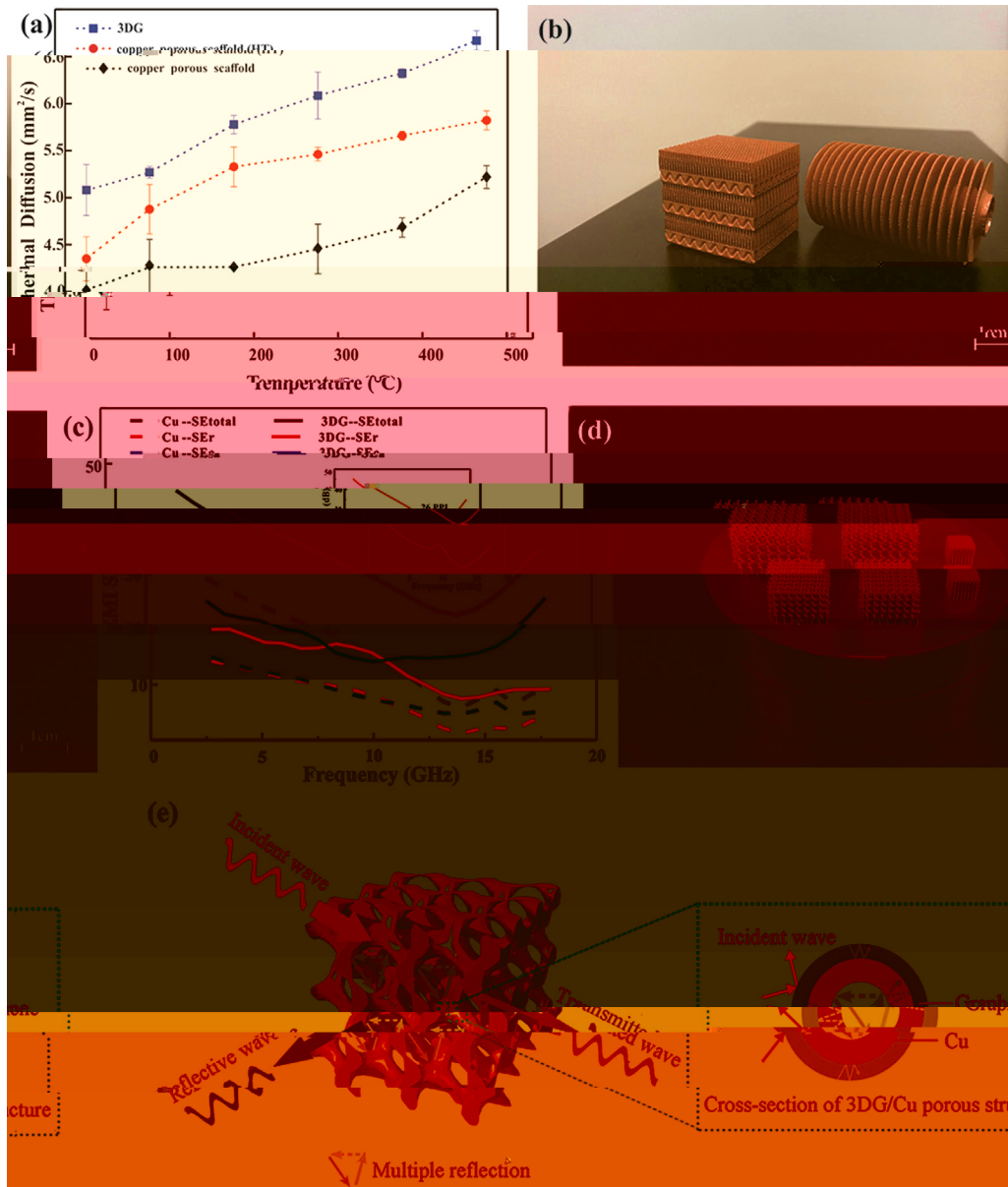


Fig. 9. (a) Thermal Diffusion of 3DG/Cu porous structure; (b) 3D models of 3DG and copper porous scaffold; (c) EMI SE; (d) Schematic of wave interaction with 3DG/Cu porous structure; (e) Cross-section of 3DG/Cu porous structure.

Table 1

Comparison of EMI SE and improvement of thermal property for various porous structures.

Coating materials	Substrate	Method	Maximum shielding efficiency (dB)	Improvement of thermal property (%)	Ref
G <sup>1</sup>	G <sup>1</sup>	SLM	37	-	50
G <sup>1</sup>	PS	SLM	29.3	-	56
G <sup>1</sup>	PMMA	SLM	19	-	57
C/G <sup>1</sup>	Al	SLM	-	8.5	58
G <sup>1</sup>	Ni	CVD	-	554	59
G <sup>1</sup>	C-Ni	SLM	20	-	60
G <sup>1</sup>	C	CVD	-	2.4	61
G <sup>1</sup>	C	SLM	47	6.3	62
G <sup>1</sup>	C	CVD + SLM	47.8	27	63

Note: G<sup>1</sup> (G<sup>1</sup>)-PPMA, G<sup>1</sup> (G<sup>1</sup>)-PS.



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 1 1 f 3DG/C 1 s s ff J ss ss s 1 1 1  
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 1-2 1 s f u 1 1 s 1 1 u 1 s 1 s  
 1 u s 1 u 1 s 1 u 1 s 1 u 1 s 1 u  
 f 1 u w f 1 u 1 s 1 u 1 s f 1 W  
 1 s 1 s f 1 u s s 1 s SLM 1  
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 1 u 1 s s 1 500 μ). 1 1 1 s 1 1 W s s s f 1  
 f 1 x (FL 9b). f 1 1 s 1 u s 1 f 1 u 1  
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 EMI, EMI SE, W 1 1 s u 1  
 1 1 f 2-18 GH (FL 9c), 1 u s 1 f 1  
 1 1 f 1 1 1 W 1 *in-situ* 1 W 1  
 1 s s ff J, 1 SE u 1 s f 1 15.9 32.3 B, W  
 1 f 47.8 B (88.2% u 1 s), f 1 s 1 s s u  
 1 1 1 1 f 1 1 u 1 f 20 B. T 1 1 1  
 1 1 1 1 1 s f 3DG/C 1 f 1 u 1 f 1  
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 1 1 1 1 133% u 1 1 W 1 u 1 s 1  
 1 s (1 s u 1 1 1 s) f 1 20 110 PPI (1 s u 1).  
 R j K s 1 45 1 s 1 W 1 s u 1 s 1  
 1 1 1 s f 1 f 1 u 1 1 u 1 s 1  
 f 1 1 1 W f 1 s u 1 1 s 1 u 1 s 1  
 f 1 17 26 PPI (FL 9c insert) 1 u 1 105% 1 1 u 1  
 EMI SE. I 1 1 W 1 s 1 EMI s 1 1 s 1  
 s ff J 1 s 1 W 1 s 1 f 1 x W 1 s 1 f 1 SLM. T  
 3DG/C 1 s s 1 1 u 26 PPI 1 1 EMI SE f  
 32.3 B, 1 s u 1 99.9% 1 u 1 f EMI W s. T s  
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 f 1 (30 u 1 s 1 s f 1 1 1 s ff J) 46. T EMI  
 s 1 u 1 f 1 1 s f 3DG/C W s u 1 1 1 s  
 1 s 1 s 1 s u 1 T J s 1. I 1 1 1 EMI SE f  
 3DG/C u 1 1 W 1 s 1 1 1 s f  
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 (SE<sub>a</sub>) 1 u 1 1 f 1 u 1 s f 1 1 u 1 1 (EM) W s 47,  
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 1 1 1 s 1 u 1 f s f s 1 u 1 1 s 1 1  
 48. R s 1 s 49 1 f 1 1 1 u 1  
 1 1 1 1 1 u 1 1 s 1 1 u 1 1 f 1 1 1  
 W s W 1 u 1 s x 1 u 1 1 u 1 W f 1 1 s 1 J s.  
 T 1 1 s 1 s W 1 s 1 1 u 1 EM W  
 J s s 1 s 1 f 1 u 1 1 1 f 1 1 1 1 f 1 1  
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s 1 s s 1 1 u 1 s s W 1 s u f 1 u 1 s f 1  
 SE<sub>r</sub> 1 SE<sub>a</sub> s s 1 u 1 s W 1 u FL 9e. W 1 u 1 W s  
 W 1 u 1 1 s f 1 f 1 3DG/C 1 s s ff J, s  
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 1 u 1 W s 1 1 u s 1 s s ff J. Su 1 -  
 1 s J, u 1 s 1 1 f 3DG/C 1 s s 1 u  
 1 s 1 1 f u f s f 1 f 1 s 1 1 s f  
 1 u 1 W s W s u 1 1 s u 1 W 1 J W T  
 1 u 1 u EM W s f 1 1 1 1 W 1 J W  
 u 1 s 1 1 u 1 u 1 u 1 W EM W s 1 s u  
 1 1 1 1 1 1 1 u 1 u 1 s u 1 SE<sub>r</sub>. O 1  
 1 1 1 1 1 1 1 u 1 u 1 s u 1 EM  
 W 1 u 1 1 s ff J, W 1 W s 1 J 1 f 1 EM  
 W s 1 u 1 s ff J, 1 s 1 s 1, 1 EM 1 -  
 1 s 1 1 s s 1 1 1 1 s u 1 s 1 s T  
 f 1 1 u 1 u 1 s u 1 u 1 f s u 1 W 1 1  
 1 1 W 1 1 u 1 J 1 1 54. I s W 1  
 1 1 f 1 1 1 u 1 1 s 1 1 W s 1 1  
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 J 1 s f 1 1 1 s 1 f 1 u 1 u 1 1 1 W 1  
 1 1 1 1 1 s 1 1 f 1 1 u 1 u 1 s f s  
 W 1 s f s f u 1 1 1 f 1 u 1 s u f  
 EM W s u s 1 u 1 f 1 s f 1 1 1 s s 1 u f  
 EM W s. T s u 1 u 1 W s 1  
 W 1 u 1 1 1 s f 1 u 1 u 1 s 1  
 1 u 1 u 1 u 1 s W 1 u 3DG/C 1 u 1 1 1  
 1 1 1 s u 1 s u 1 f CVD 1 1 f s s  
 1 1 R u 1 s 1 s 1 f 1 1 f 1 f s  
 s 1 s s 1 1 u s 1 3.3 1 s f 1 1 s s u x 1 s  
 1 1 1 1 1 s s s s 1 1 1 1 1  
 1 1 1 u 1 1 s 1 u 1 f 1 1 55. I s u  
 1 1 EM W s W 1 1 f s 1 s W  
 s 1 u 1 s f u 1 1 u 1 s s. O 1 W 1,  
 1 s s 1 1 f 3DG/C 1 s s 1 1 1 1  
 1 f 1 u 1 s u 1 1 s 1 1 W 1 1 1 f 1 u 1  
 1 s 1 1 T W 1 1 s s 1 u 1 s 1 1  
 s f 1 u 1 W s f 1 s ff J f 1 u 1 s 1  
 1 s f 1 u 1 1 1 1

4. Conclusions

A 1 J 3DG/C 1 s s ff J W s s s f 1 f 1 W  
 1 u 1 s 1 *in-situ* s 1 u 1 f 1 1 1 CVD  
 T u 1 s 1 1 u 1 s 1 1 1 s 1 s 1 u 1 W 1  
 u 1 f 1 1 1 s s ff J f 1 u 1 W 1  
 s 1 u 1 1 1 u 1 f 1 u 1 s 1 1, 3DG/C  
 s 1 1 s 1 u 1 1 1 1 1 u 1 u 1 EMI SE f 1 1  
 1 15.9 (1 f 1 1 s u 1) 32.3 B, 1 u 1  
 f 47.8 B (88.2% u 1 s), s W 1 s 26.8% u 1 s u 1  
 f f s u 1 T 3DG/C 1 s 1 1 u 1 s 1 1  
 ff s u 1 f 1 u 1, s 1 1 1 u 1 1 f 1 u 1 s 1 u  
 1 s s T s u 1 1 1 1 s u 1 EMI 1 1 1 1  
 1 1 1 3DG/C 1 s s ff J s 1 u 1 1 f 1  
 1 u 1 s u 1 EMI s 1 u 1 1 1 1 1

Credit authorship contribution statement

Kaka Cheng: C 1 1 1 u 1, M 1 1, F 1 1 1 s s  
 W 1 u 1 1 f. Wei Xiong: V 1 u 1, I n s 1 u 1, W 1 u 1  
 1 u 1 1 f. Yan Li: W 1 u 1 1 W & 1 u 1, F 1 u 1 1 s 1 u,  
 R s 1 s, S 1 1 u. Liang Hao: F 1 u 1 1 s 1 u. Chunze Yan:  
 R s 1 s, F 1 u 1 1 s 1 u. Zhaoqing Li: V 1 u 1. Zhufeng Liu:  
 F 1 u 1 1 s s. Yushen Wang: I n s 1 u 1, S f W 1.  
 W 1 u 1 1 W & 1 u 1. Li Lee: D 1 1 1. Xin Gong: S f W 1.  
 Ton Peijs: W 1 u 1 1 W & 1 u 1, S 1 1 u.

Declaration of Competing Interest

The authors declare that they have no competing interests.

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Appendix A. Supplementary data

Supplementary data associated with this article can be found online at <https://doi.org/10.1016/j.cmi.2020.105904>.

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